

TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimensions: 17.40Lx16.50Wx2.70Hmm
 Contact principle: Friction technology
 Operating position: shaft up/down/Horizontal
 Mounting System: SMT Type (without post)
 Durability: 2,000 cycles min.

2. Mechanical characteristics:

Insulation material: LCP

3. Electrical Characteristics

Number of contacts : 8pins
 contact resistance: 100m Ω /20mA
 insulation resistance: >1000M Ω /500VDC

4. Solderability

wave: Not applicable
 Vaporphase: 215°C, 30sec. Max
 IR reflow: 250°C - 260°C, 5 sec. Max.
 Manual soldering : 360°C, 3sec. Max

5. Environmental Characteristics

Operating temperature: -25°C~+85°C
 Operating humidity : 10%~+95%RH
 Storage temperature: -40°C~+85°C
 Storage Humidity: 10%~95%RH
 thermal shock: -40°C~+85°C, 5cycles
 Damp Heat: 40°C, 90%RH, 10days.
 Salt-Mist: 35°C, 5%NaCl, 24H

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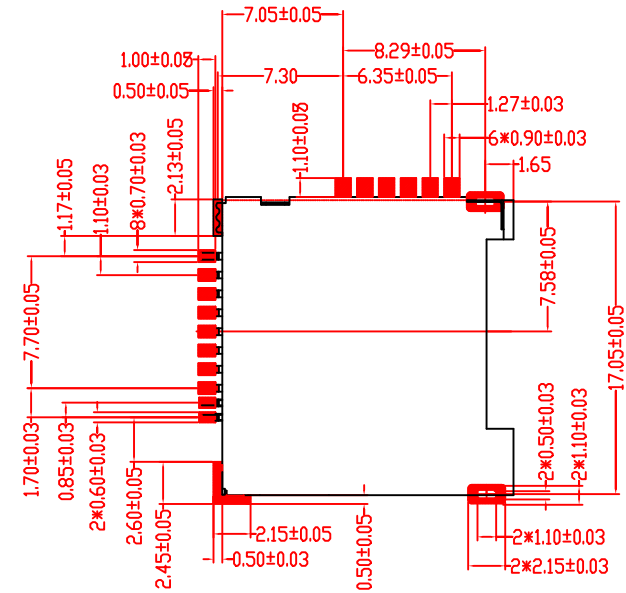
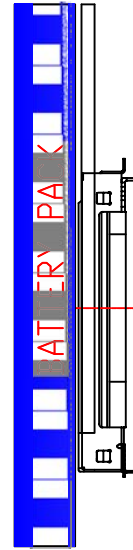
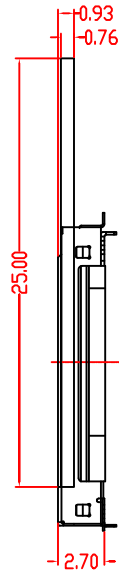
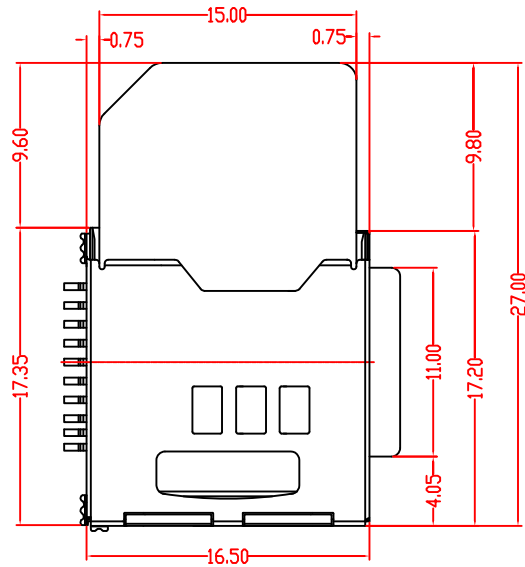
SIM+TF Card Connector

Model NO : 618

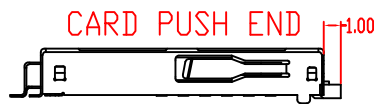
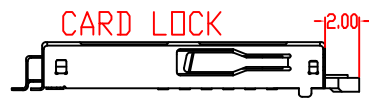
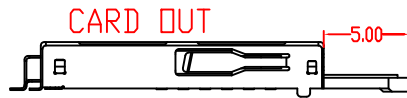
Memory Card Connector

REVISION: 1.0

DATE: APR.12. 2007



PCB PATTERN



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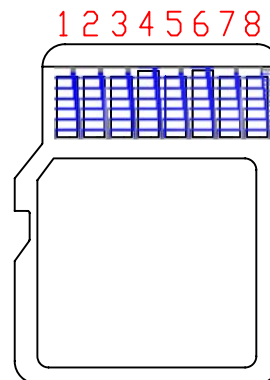
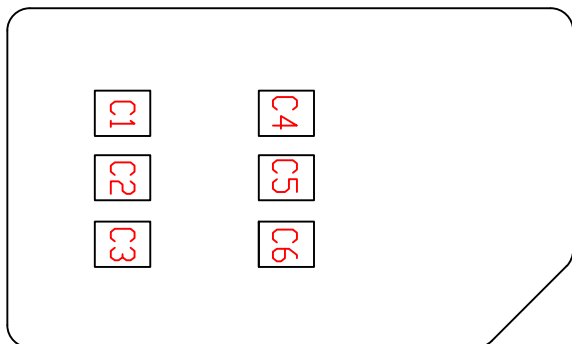
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SIM CARD

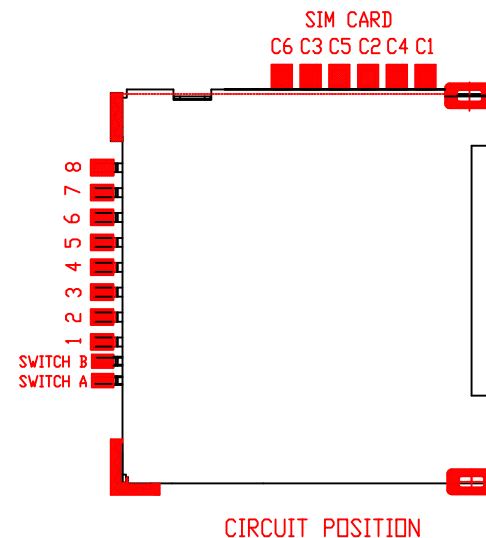
Pin No.	NAME
C1	ACC
C2	RST
C3	CNK
C4	CND
C5	VPP
C6	I/O

T-FLASH CARD

Pin No.	NAME	TYPE	DESCRIPTION
1	DAT2	I/O/PP	Date Line[bit2]
2	CD/DAT3	I/O/PP	Card Detect Date Line[bit3]
3	CMD	PP	DESCRIPTION
4	VDD	S	DESCRIPTION
5	CLK	I	DESCRIPTION
6	ASS	8	DESCRIPTION
7	DAT0	I/O/PP	DESCRIPTION
8	DAT1	I/O/PP	DESCRIPTION



T-FLASH CARD



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